







## **FABRICATIONS NOTES**

- 1. MATERIAL FR4 - LAYERS: 2 - CU: 10Z TICKNESS: 1,6 mm
- 2. SUFACE FINISH SELECTIVE SN - PB
- 3. SOLDERMASK
  SOLDERMASK OVER BARE COPPER
  LIQUID PHOTO-IMAGEABLE (LPI)
  TOP COLOR: GREEN
  BOTTOM COLOR: GREEN
- 4. SILKSCREEN
  EPOXY NON CONDUCTIVE
  TOP COLOR: WHITE
  BOTTOM COLOR: WHITE
- 5. PACKAGING REQUIREMENTS
  PACKAGED IN VACUUM SEALED INNER CONTAINERS

Layer	Name	Material	Thickness	Constant	Board Layer Stac	Ξk
1	Top Overlay					77
2	Top Solder	Solder Resist	0,010mm	3,5		//
3	Top Layer	Copper	0,036mm			//
4	Dielectric 1	FR-4	1,500mm	4,8		//
5	Bottom Layer	Copper	0,036mm			$\mathbb{Z}$
6	Bottom Solder	Solder Resist	0,010mm	3,5		$\mathbb{Z}$
7	Bottom Overlay					$\mathbb{Z}$

			TIT	
				1
DRAWN	Luciano Aguerre	14.05.2021	TOLERANCES UNLESS	
CHECKED			OTHERWISE NOTED	DMG
APPROVED			LINEAR 0,2mm	
APPROVED			ANGULAR 1	

TITLE
MODULO DE TESTEO PARA BURN IN

REV A

DWG SIZE	PART N# TEST-MODULE-ECO		
H3	SCALE 1:1	SHEET 1 OF 1	